

ABSTRACT OF THE DISCLOSURE

A copper electroplating material capable of exhibiting increased easy-dissolution properties, to thereby minimize formation of an insoluble residue. Basic copper carbonate is formed in a reaction tank by deposition and heated to a temperature of between 250°C and 800°C and preferably between 350°C and 600°C in an atmosphere which does not form a reducing atmosphere which does not form a reducing atmosphere, to thereby be subjected to thermal decomposition, resulting in providing easily soluble copper oxide. The copper oxide is washed with water and dewatered using, for example, a centrifugal separator. Then, the copper oxide is dried.

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